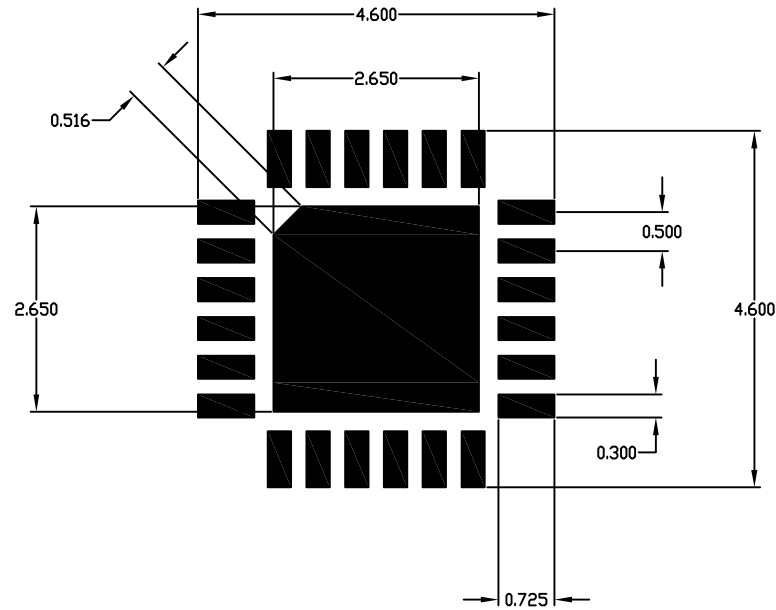




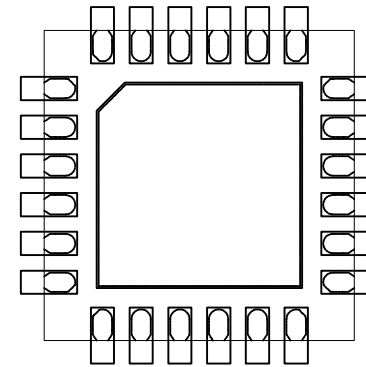
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DOCUMENT ID #: 90-100273
REVISION: A-000
DOCUMENT TITLE: PACKAGE LAND PATTERN, [T2444+28C / T2444
EFFECTIVE DATE: 09/16/2024
EXPIRATION DATE:
CHANGE NUMBER: 1216856
ORIGINATOR: Aurelio Giron Jr.

REASON FOR CHANGE:
INITIAL RELEASE

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100791 / 21-100790
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

—DRAWING NOT TO SCALE—



This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depends on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <https://www.analog.com/en/support> for further questions.

TITLE:
PACKAGE LAND PATTERN,
[T2444+28C / T2444Y+28C] TQFN-CU

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